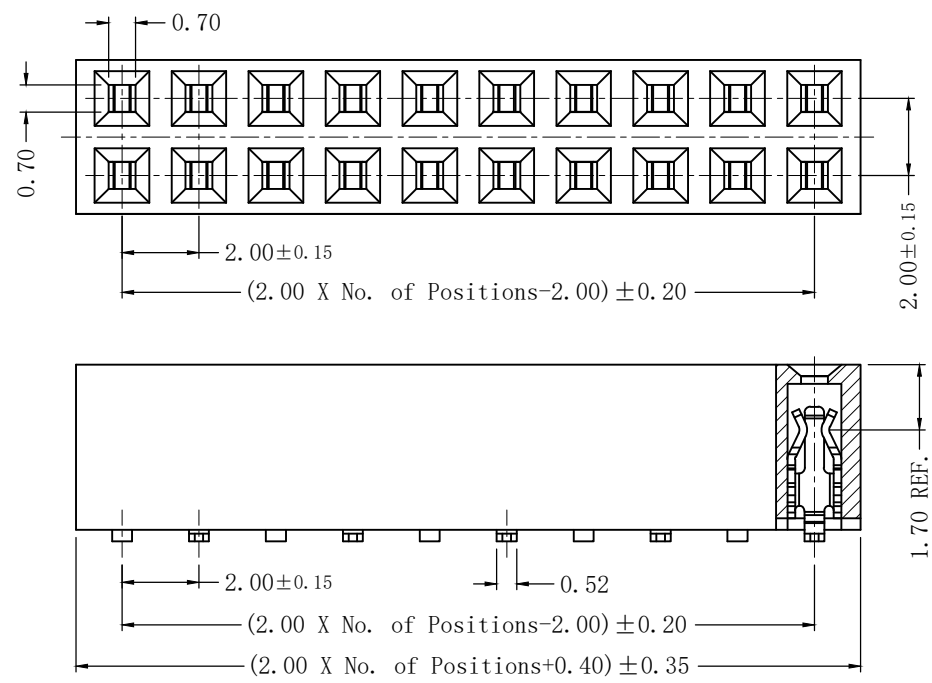
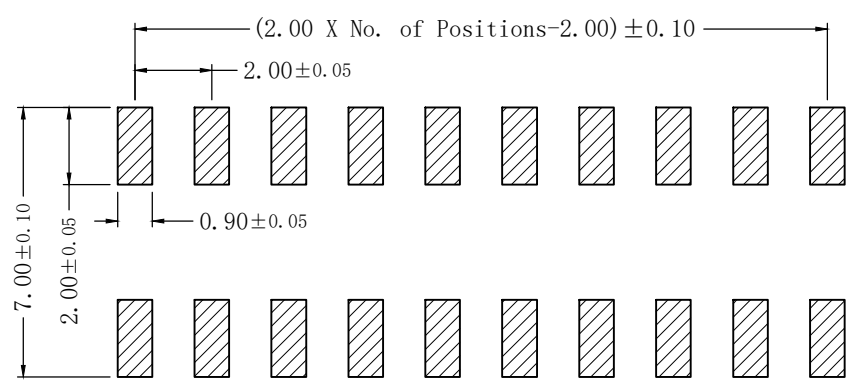


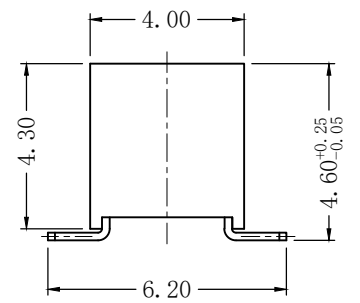
版次	变更内容	审核	日期



弯曲度: 2\*02P ~ 2\*20P 0.30 MAX.  
 2\*21P ~ 2\*30P 0.40 MAX.  
 2\*31P ~ 2\*40P 0.50 MAX.



Recommended PCB Layout



203-2SMD-3C-2\*xxP G-A

单排芯数 01~40P

电镀

G: 镀金Gold Flash  
 1G: 镀金1u"  
 3G: 镀金3u"  
 (镀金可订制)

塑高 4.3: 4.30mm

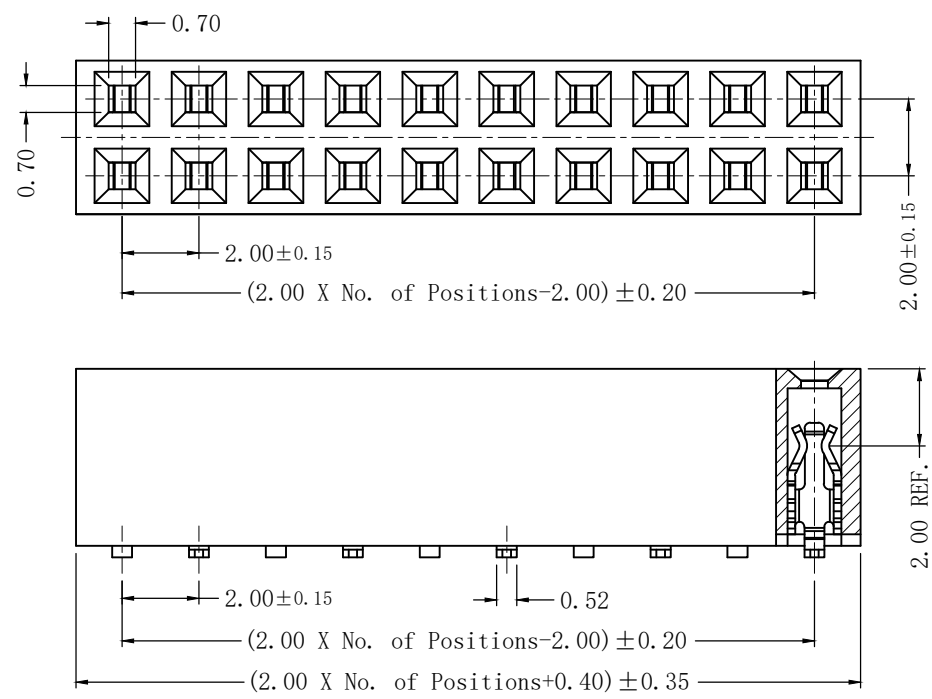
技术参数: SPECIFICATIONS

额定电流 (Current Rating): 1.5A  
 绝缘电阻 (Insulation Resistance): 1000MΩ Min.  
 接触电阻 (Contact Resistance): 20m Ω Max.  
 额定电压 (Dielectric Withstanding Voltage): AC 500V  
 工作温度 (Operating Temperature): -40 °C ~ +105 °C  
 最大加工温度 (Max Processing Temp): (230 °C for 30~60 seconds)  
 (260 °C for 10 seconds)

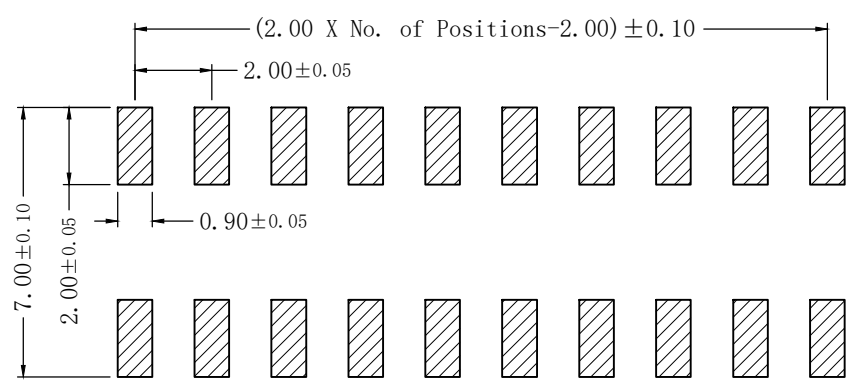
接触材料 (Contact Material): 磷青铜(Phosphor Bronze), THICKNESS 0.15mm  
 塑胶材料 (Insulator Material): 尼龙(Nylon)-9T, UL 94V-0, 颜色: 黑色  
 接触电镀 (Contact Plating): 镀金 (Gold plated)  
 (电镀规格可根据客户要求来定制)  
 Opitonal planting on request.

公差:	版次:	A	上海宗进电子科技有限公司 Shanghai Zong Jin Electron Technology Co.LTD			
. X ±0.35 . XX ±0.25 . XXX LNLB ±2°	比例:		型号:	203-2SMD-3C-2*xxPG-A	签名	日期
	单位:	mm	描述:	2.0双排贴板排母	绘图:	
	页码:	1/3	图号:		确认:	
	⊕	☐			审核:	

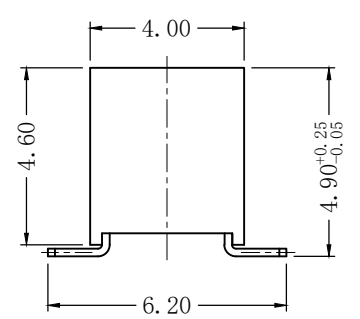
版次	变更内容	审核	日期



弯曲度: 2\*02P ~ 2\*20P 0.30 MAX.  
 2\*21P ~ 2\*30P 0.40 MAX.  
 2\*31P ~ 2\*40P 0.50 MAX.



Recommended PCB Layout



203-2SMD-3C-2\*xxP G-A

单排芯数 01~40P

电镀 G: 镀金Gold Flash  
 1G: 镀金1u"  
 3G: 镀金3u"  
 (镀金可订制)

塑高 4.6: 4.60mm

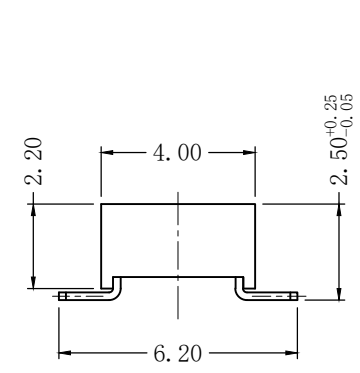
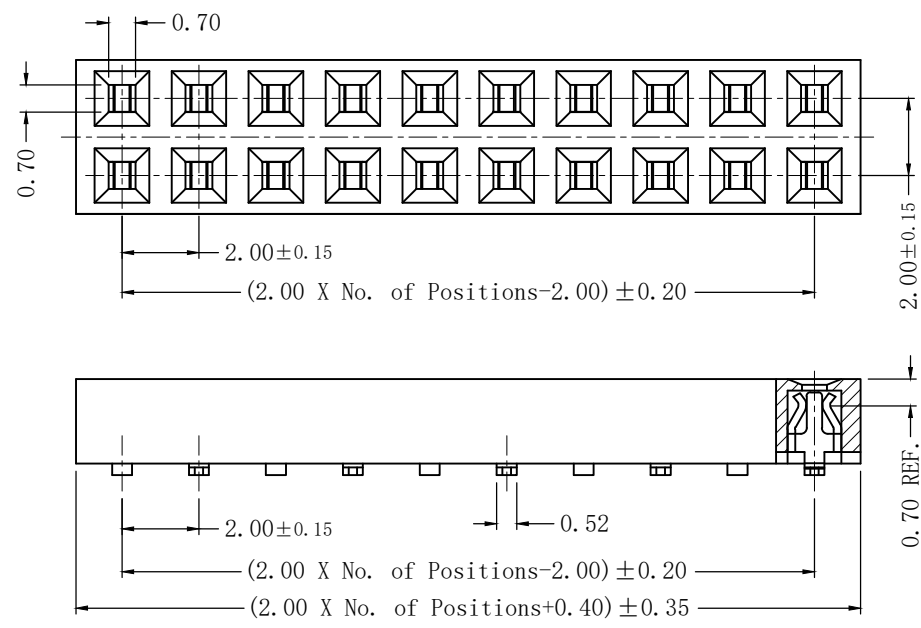
技术参数: SPECIFICATIONS

额定电流 (Current Rating): 1.5A  
 绝缘电阻 (Insulation Resistance): 1000MΩ Min.  
 接触电阻 (Contact Resistance): 20m Ω Max.  
 额定电压 (Dielectric Withstanding Voltage): AC 500V  
 工作温度 (Operating Temperature): -40°C ~ +105°C  
 最大加工温度 (Max Processing Temp): (230°C for 30~60 seconds)  
 (260°C for 10 seconds)

接触材料 (Contact Material): 磷青铜(Phosphor Bronze), THICKNESS 0.15mm  
 塑胶材料 (Insulator Material): 尼龙(Nylon)-9T, UL 94V-0, 颜色: 黑色  
 接触电镀 (Contact Plating): 镀金 (Gold plated)  
 (电镀规格可根据客户要求来定制)  
 Opitonal planting on request.

公差:	版次:	A	上海宗进电子科技有限公司 Shanghai Zong Jin Electron Technology Co.LTD			
. X ±0.35 . XX ±0.25 . XXX ±2° LNLB	比例:		型号:	203-2SMD-3C-2*xxPG-A	签名	日期
	单位:	mm	描述:	2.0双排贴板排母	绘图:	
	页码:	2/3	图号:		确认:	
	⊕	⏏			审核:	

版次	变更内容	审核	日期



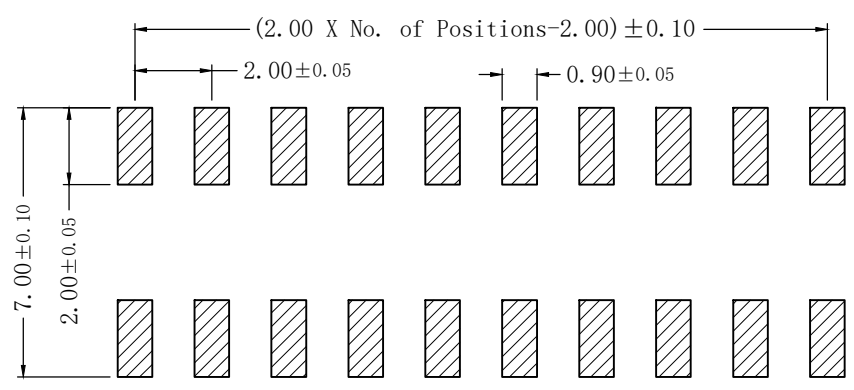
203-2SMD-3C-2\*xxP G-A

单排芯数 01~40P

电镀  
G: 镀金Gold Flash  
1G: 镀金1u"  
3G: 镀金3u"  
(镀金可订制)

塑高 2.2: 2.20mm

弯曲度: 2\*02P ~ 2\*20P 0.30 MAX.  
2\*21P ~ 2\*30P 0.40 MAX.  
2\*31P ~ 2\*40P 0.50 MAX.



Recommended PCB Layout

技术参数: SPECIFICATIONS

额定电流 (Current Rating): 1.5A  
 绝缘电阻 (Insulation Resistance): 1000M Ω Min.  
 接触电阻 (Contact Resistance): 20m Ω Max.  
 额定电压 (Dielectric Withstanding Voltage): AC 500V  
 工作温度 (Operating Temperature): -40 °C ~ +105 °C  
 最大加工温度 (Max Processing Temp): (230 °C for 30~60 seconds)  
 (260 °C for 10 seconds)

接触材料 (Contact Material): 磷青铜(Phosphor Bronze), THICKNESS 0.15mm  
 塑胶材料 (Insulator Material): 尼龙(Nylon)-9T, UL 94V-0, 颜色: 黑色  
 接触电镀 (Contact Plating): 镀金 (Gold plated)  
 (电镀规格可根据客户要求来定制)  
 Opitonal planting on request.

公差:	版次:	A	上海宗进电子科技有限公司 Shanghai Zong Jin Electron Technology Co.LTD			
. X ±0.35 . XX ±0.25 . XXX LNLB ±2°	比例:		型号:	203-2SMD-3C-2*xxPG-A	签名	日期
	单位:	mm	描述:	2.0双排贴板排母	绘图:	
	页码:	3/3	图号:		确认:	
	⊕	☐			审核:	